

TEMIC

Siliconix

2N6660JAN/JANTX/JANTXV

N-Channel Enhancement-Mode MOS Transistors

Product Summary

$V_{(BR)DSS}$ Min (V)	$r_{DS(on)}$ Max (Ω)	$V_{GS(th)}$ (V)	I_D (A)
60	3 @ $V_{GS} = 10$ V	0.8 to 2	0.99

Features

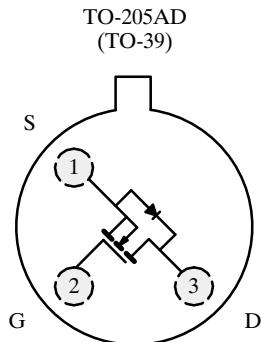
- Military Qualified
- Low On-Resistance: 1.3Ω
- Low Threshold: 1.7 V
- Low Input Capacitance: 35 pF
- Fast Switching Speed: 8 ns
- Low Input and Output Leakage

Benefits

- Guaranteed Reliability
- Low Offset Voltage
- Low-Voltage Operation
- Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

Applications

- Military Applications
- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays



Top View

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	0.99	A
		0.62	
Pulsed Drain Current	I_{DM}	3	
Power Dissipation	P_D	6.25	W
		0.725	
Maximum Junction-to-Ambient ^b	R_{thJA}	170	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Case	R_{thJC}	20	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

Notes

- a. Pulse width limited by maximum junction temperature.
b. Not required by Military Spec.

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Specifications^a

Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ ^b	Max	
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 10 µA	60	75		
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 1 mA	0.8	1.7	2	V
		T _C = -55°C			2.5	
Gate-Body Leakage	I _{GSS}	T _C = 125°C	0.3			nA
		V _{DS} = 0 V, V _{GS} = ±20 V			±100	
Zero Gate Voltage Drain Current	I _{DSS}	T _C = 125°C			±500	µA
		V _{DS} = 48 V, V _{GS} = 0 V			1	
On-State Drain Current ^c	I _{D(on)}	T _C = 125°C			100	A
		V _{DS} = 10 V, V _{GS} = 10 V		2		
		V _{GS} = 5 V, I _D = 0.3 A		2	5	
Drain-Source On-Resistance ^c	r _{D(on)}	V _{GS} = 10 V, I _D = 1 A		1.3	3	Ω
		T _C = 125°C		2.4	5.6	
Forward Transconductance ^c	g _{fs}	V _{DS} = 7.5 V, I _D = 0.525 A	170	350		mS
Diode Forward Voltage	V _{SD}	I _S = 0.99 A, V _{GS} = 0 V	0.7	0.8	1.6	V
Dynamic						
Input Capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V f = 1 MHz		35	50	pF
Output Capacitance	C _{oss}			25	40	
Reverse Transfer Capacitance	C _{rss}			7	10	
Drain-Source Capacitance	C _{ds}			30		
Switching^d						
Turn-On Time	t _{ON}	V _{DD} = 25 V, R _L = 23 Ω I _D ≈ 1 A, V _{GEN} = 10 V R _G = 25 Ω		8	10	ns
Turn-Off Time	t _{OFF}			8.5	10	

Notes

- a. T_A = 25°C unless otherwise noted.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Pulse test: PW ≤ 300 µs duty cycle ≤ 2%.
- d. Switching time is essentially independent of operating temperature.
- e. For typical characteristics curves see the 2N6659/2N6660, VQ1004J/P data sheet.

VNDQ06